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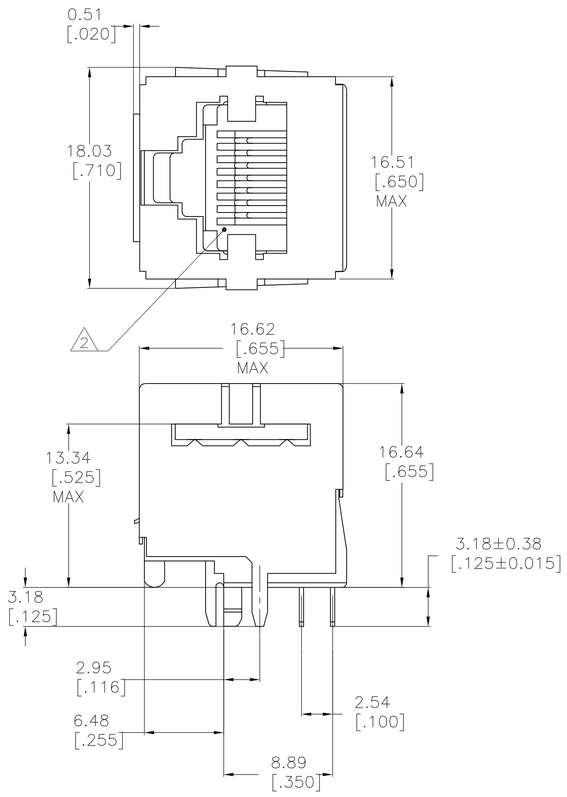
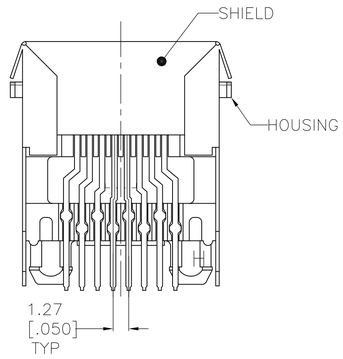
LOC	DIST
AA	00

REVISIONS

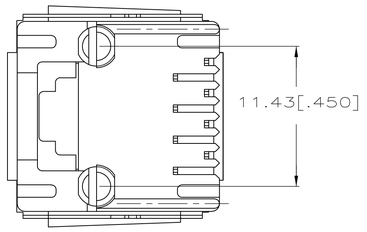
P	LTR	DESCRIPTION	DATE	DWN	APVD
	C	ECO-07-021363	25SEPT07	LAM	PR

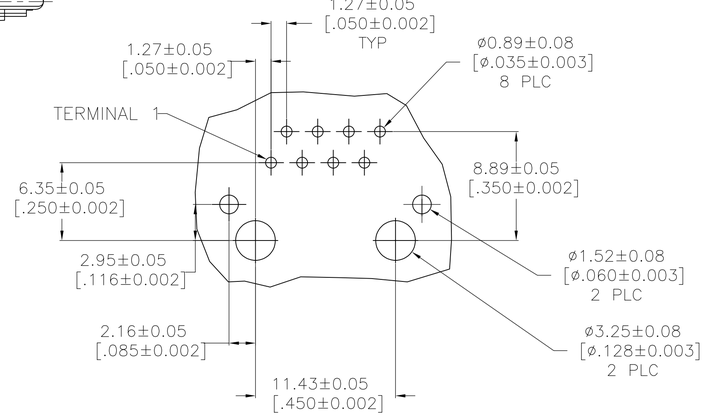




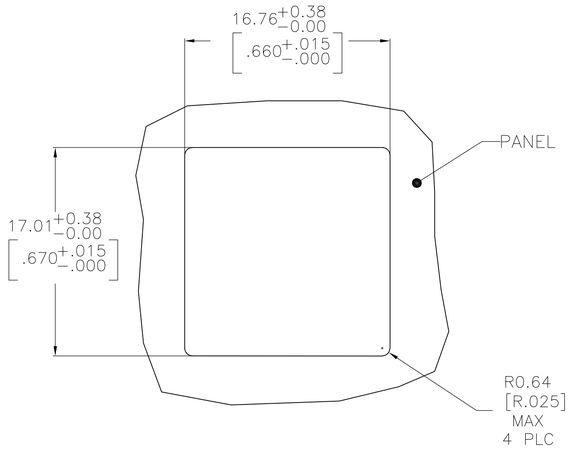
1. MATERIAL:
   HOUSING – POLYESTER MOLDING COMPOUND, COLOR: BLACK
   TERMINALS – 0.35[.0138] THICK PHOS BRONZE PLATED WITH 1.27µm[.000050] MIN THICK GOLD IN LOCALIZED AREA AND 3.81µm[.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27µm[.000050] MIN THICK NICKEL UNDERPLATE
   SHIELD – COPPER ZINC ALLOY PLATED WITH 3.0µm [.000120] MIN THICK REFLOWED TIN.

△2 CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.





RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT
COMPONENT SIDE SHOWN



RECOMMENDED PANEL CUTOUT

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm [INCHES]

TOLERANCES UNLESS OTHERWISE SPECIFIED:
0 PLC ± –
1 PLC ± –
2 PLC ± –
3 PLC ± 0.13[.005]
4 PLC ± –
ANGLES ± –

MATERIAL: SEE NOTE 1
FINISH: SEE NOTE 1

DWN: L. VARELA – DOCKS 15JUN2005
CHK: J. WESTMAN 15JUN2005
APVD: S. FLICKINGER 15JUN2005
PRODUCT SPEC: 108-1163
APPLICATION SPEC: 114-2048
WEIGHT: –

Tyco Electronics
Tyco Electronics Corporation
Harrisburg, PA 17105-3608

NAME: MODULAR JACK ASSEMBY, TOP ENTRY, 8 POSITION, SHIELDED, WITH PANEL STOPS, PCB AND PANEL GROUNDS (IR COMPATIBLE)

SIZE	CAGE CODE	DRAWING NO	RESTRICTED TO
A1	00779	C-6368115	–

CUSTOMER DRAWING | SCALE 4:1 | SHEET 1 OF 1 | REV C

6368115-1
PART NO